

	Hit s	Search Text	DBs
10	2	430/311.ccls. and ((semiconductor or wafer or substrate) near9 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5)) near12 (cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture)) and (encapsulat\$4 near9 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	7	257/434.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5)) near14 (cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture)) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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12	7	257/433.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) same ((cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture)) same (photosensitive or light\$4sensitive or epoxy or photo\$4cur\$4 or resist or photoresist)) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	3	257/435.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) same ((cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4) and (photosensitive or photocur\$4 or cur\$4 or epoxy or resist or photoresist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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14	12	257/434.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5) or image)) and (((cover or lid or plate or template or encapsula\$5) near13 (shield or (transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture or screen\$4 or silk\$4screen\$4))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4) and ((spacing or support) same (structure or region or area))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	15	250/239.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5) or image)) same ((cover or lid or plate or template or encapsula\$5) near13 (shield or (transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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16	1	250/239.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) same ((cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4) and (photosensitive or photocur\$4 or cur\$4 or epoxy or resist or photoresist) and ((support or spacing) near9 (structure or region))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
17	3	250/208.1.ccls. and (((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) same ((cover or lid or plate or template or encapsula\$5) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4) and (photosensitive or photocur\$4 or cur\$4 or epoxy or resist or photoresist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

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18	79	250/239.ccls. and ((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5) or image)) and (((cover or lid or plate or template or encapsula\$5) near13 (shield or (transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6 or aperture or screen\$4 or silk\$4screen\$4))) and ((encapsulat\$4 near9 packag\$4) or housing or packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB